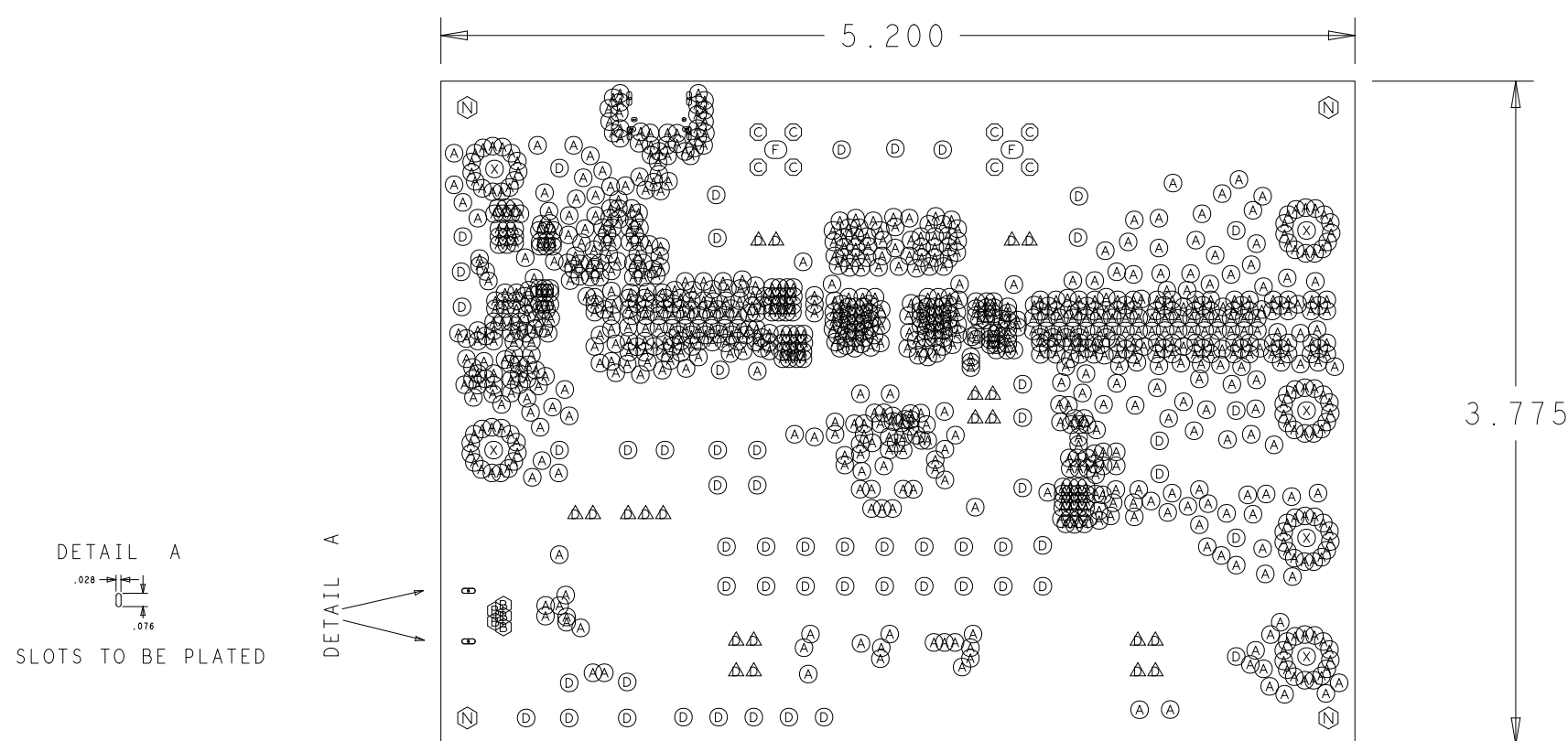


NOTES:

- THIS IS A 6 LAYER BOARD WITH COMPONENTS ON BOTH SIDES.
- PRINTED CIRCUIT BOARD SHALL BE 2 OUNCE COPPER.
BOARD MATERIEL TO BE EXPOXY BASED FR-4.
- SMOBC SOLDERMASK BOTH SIDES USING BLUE RESIST. IAW IPC-SM-840
- SILKSCREEN BOTH SIDE(S) USING WHITE NON CONDUCTIVE EPOXY BASED
INK. TRIM ALL SILKSCREEN 4mils FROM BARE COPPER
- MANUFACTURE/FABRICATE TO MEET EU RoHS DIRECTIVE.
ALL MATERIALS AND SOLDERMASK TO BE COMPLIANT TO EU RoHS
DIRECTIVE 20002/95/EC
LAMINATE AND RESIN MATERIAL PARAMETERS
Tg > 170 C
Td > 294 C
- ELECTROLESS NICKEL GOLD OR IMMERSION GOLD BOARD FINISH.
- MINIMUM TRACE WIDTH 8 MILS/ SPACE 6 MILS
- VIAS IN PADS TO BE FILLED WITH NON-CONDUCTIVE EPOXY.



DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	FINISHED SIZE	ROTATION	PLATED	QTY
⊙	10.0	-	PLATED	991
⊗	28.0	-	PLATED	5
⊙	37.0	-	PLATED	8
⊗	40.0	-	PLATED	56
△	41.0	-	PLATED	21
⊖	65.0	-	PLATED	2
⊙	155.0	-	PLATED	6
•	23.62	-	NON-PLATED	1
⊗	128.0	-	NON-PLATED	4
■	49.21x27.56	0.000	PLATED	2
⊞	74.8x23.62	90.000	PLATED	2
∞	76.0x28.0	0.000	PLATED	2
⊞	78.74x27.56	90.000	PLATED	2
•	33.46x23.62	0.000	NON-PLATED	1

TOTAL HOLES: 1103

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